

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE  
UNITED STATES RECEIVING OFFICE (RO/US)

In re Application of: Francis Bourrieres, et al  
U.S. Nat'l Stage of PCT/FR00/00018  
Int'l App. No.:  
Int'l Filing Date: 6 January 2000  
For: Method For Making Electronic Modules  
With Ball Connector Or With Integrated  
Preforms Capable Of Being Soldered On A  
Printed Circuit And Implementing Device

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11-1-01

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Commissioner for Patents  
Washington, D.C. 20231

Docket No.: N48.2-9735

## PRELIMINARY AMENDMENT

Before calculating the fees in this application, please amend the above-identified application as indicated below:

In the Abstract:

Insert the abstract page 19, enclosed herewith.

In the Claims:

Replace original claims 1-9 with claims 1-9 as follows:

- 1) (Amended) Method for producing an electronic module in the shape of a ball housing combining a network of balls (7) or geometrically identical preform connectors or shield system and surface-mounted components (2) on the same side of a substrate (1), thus making this module directly connectable by soldering to a printed circuit (3), wherein soldering cream (8) is deposited simultaneously for the components and the connecting ball or shield system located on the same surface;
- said components are transferred onto the corresponding mounting lands;
- the ball connectors with a diameter greater than the height of said components are transferred collectively onto the lands of the same side intended for them by an appropriate device; and
- a single re-melting cycle permits simultaneous soldering of the components and the connecting balls or shields onto the substrate.

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